TOPTEK PCB

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拓普线路
TOPTEK PCB

OUR PROFILE

From design o–o to assembly

We are a full-service EMS(electronics manufacturing service) provider specializing in low-to-middle volume printed circuit board assembly and fabrication.

01 ABOUT US »

Professional PCB & PCBA Manufacturer

Provide one-stop quick turnkey services from PCB manufacturing, PCB assembly, components sourcing etc. (We specialize in High multi-layer PCB (upto 80L), HDI PCB, Rigid-flex PCB, and assembly.)

In business since 2012, Toptek PCB Co.ltd has established itself as a PCB company for prototype and mid-to-mass volume PCB fabrication services.

We successfully passed ISO9001, ISO14001 and UL certification in 2013. And our production capacity exceeded 20,000 square meters/month in 2016. In 2017, we established an Overseas Sales Department dedicated to developing overseas markets. Our customers are primarily in the United States, Germany, Italy, the UK, and Canada, in various industries.

In order to meet the needs of our customers' development, we established LanShun Technology(LS ELECTRONIC) in 2019 to start focusing on PCBA services.

We have passed the ISO9001:2015 quality management system, ISO 14001:2015 environmental management systems, ISO13485:2016 medical quality management system, and IATF16949 automotive quality management system. With a group of engineering teams with more than ten years of accumulation and a professional electronic components procurement team, we serve many domestic and foreign customers in various industries, such as automotive electronics, medical electronics, power communication, industrial automation smart home, etc. We are a one-stop comprehensive manufacturing service provider integrating PCB manufacturing, electronic components sourcing, SMT placement processing and testing and assembly.

02 OUR » CERTIFICATES

Qualification certificate

IATF 16949:2016

The requirements of a quality management system for organizations in the automotive industry

ISO 13485:2016

International Organization for Standardization ISO 9001

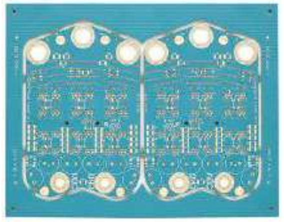
CERTIFIED ISO 14001:2015 COMPANY

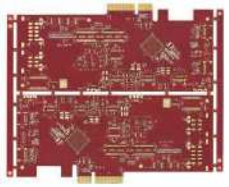
RoHS

COMPLIANT · COMPLIANT · COMPLIANT REACH

03 PRODUCT DISPLAY »

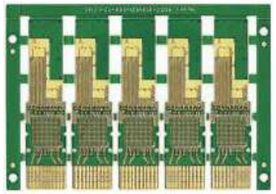
Layers	12L
Thickness	3.73mm
Material	S1000-2M
Min. via	0.3mm
Min.line width/space:	11.8/8mil
Surface treatment	ENIG:2u"
Special process	Skyblue soldermask，Heavy copper 2/3/3/3/3/3/3/3/3/3/3/2OZ





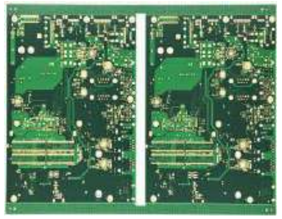
Layers	10L
Thickness	1.58mm
Material	Tachyon 100g+IT 180A
Min. via	0.2mm
Min.line width/space:	3.1/3.5mil
Surface treatment	ENIG:2u"+Hard gold fingers:30u"
Special process	High speed material+High TG Mix

Layers	10L
Thickness	1.0mm
Material	IT968TC+S1000-2M
Min. via	laser drilling:0.1mm、mechanical hole:0.15mm
Min.line width/space:	4/4mil
Surface treatment	Gold plating:2u"+Selective hard gold:50u"
Special process	Fiber optic communication， High speed material+High TG Mix

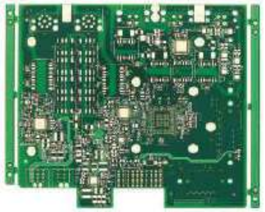


Layers	10L
Thickness	1.55mm
Material	IS400
Min. via	0.15mm
Min.line width/space:	4/4mil
Surface treatment	ENIG:2u"+Hard gold fingers:20u"
Special process	Vias fill with resin、Hard gold fingers

Layers	14L
Thickness	1.55mm
Material	IT180A
Min. via	Laser drilling0.1mm、mechanical hole:0.15mm
Min.line width/space:	3.5/4mil
Surface treatment	ENIG:4u"
Special process	blind via: L1-L2,L2-L3,L14-L13,L13-L12; buried via:L3-L12;Vias fill with resin

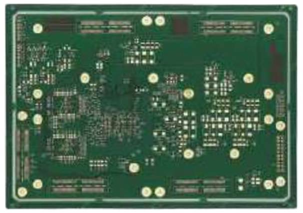


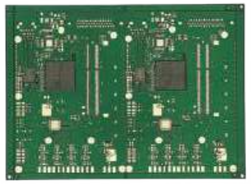
Layers	10L
Thickness	1.57mm
Material	TU872SLK
Min. via	laser drilling:0.1mm、mechanical hole:0.15mm
Min.line width/space:	3.5/4mil
Surface treatment	ENIG:3u"+Hard gold fingers:30u"
Special process	High speed material，Semi gloss Green solder mask



Layers	8L
Thickness	1.64mm
Material	"FR4 TG150 HF Nanya NPG150"
Min. via	0.2mm
Min.line width/space:	4/4mil
Surface treatment	ENIG:2u"
Special process	Nanya NPG150

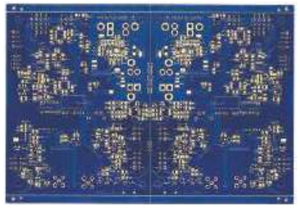
Layers	16L
Thickness	2.5mm
Material	IT180A
Min. via	0.25mm
Min.line width/space:	4/4mil
Surface treatment	ENIG:2u"
Special process	via fill with copper/Split Copper





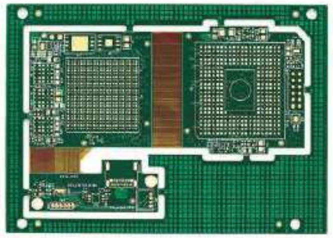
Layers	10L
Thickness	1.0mm
Material	Nelco 4000-13EP
Min. via	0.25mm
Min.line width/space:	5/5mil
Surface treatment	ENIG:2u"

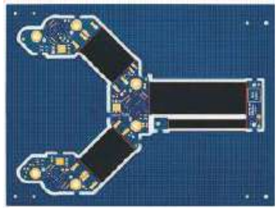
Layers	6L
Thickness	1.9mm
Material	FR4 TG150
Min. via	0.25mm
Min.line width/space:	5mil/6mil
Surface treatment	ENIG:2u"
Special process	via fill with copper/peelable mask/2oz



04 PRODUCT DISPLAY »

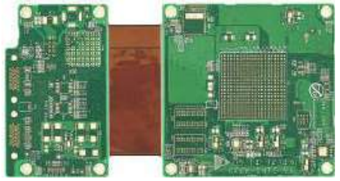
Layers	14L
Thickness	1.58mm
Material	FR408 + RF775 + FR0110
Min. via	0.25mm
Min.line width/space:	4/4mil
Surface treatment	EING:2u"
Special process	High-speed camera products， Blind holes:L1-L7/L8-L14

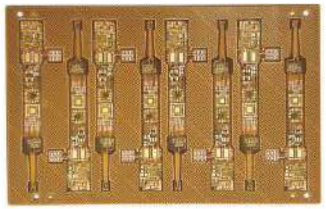




Layers	6L
Thickness	1.02mm
Material	S1000-2M+SF202+FHK1025+Tatsuta SF-PC5600
Min. via	0.25mm
Min.line width/space:	6/6mil
Surface treatment	EING:2u"
Special process	Vias fill with resin

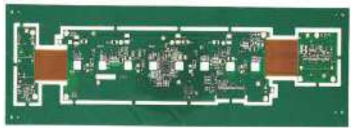
Layers	13L
Thickness	1.6mm
Material	S1000-2M+ SF202
Min. via	0.2mm
Min.line width/space:	3.5/4mil
Surface treatment	ENIG:2u"



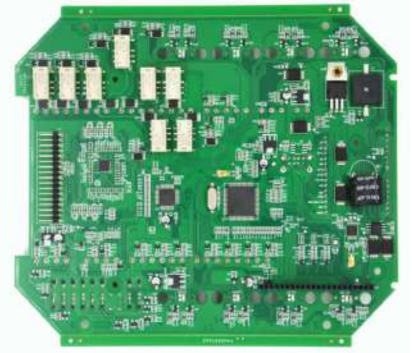


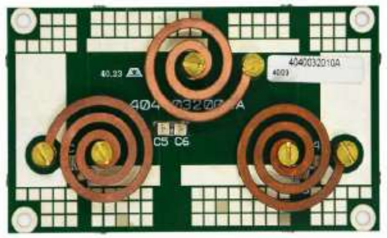
Layers	4L
Thickness	0.22mm
Material	SF202+FHT0525
Min. via	0.1mm
Min.line width/space:	6/4mil
Surface treatment	ENIG:2u"
Special process	Vias fill with resin

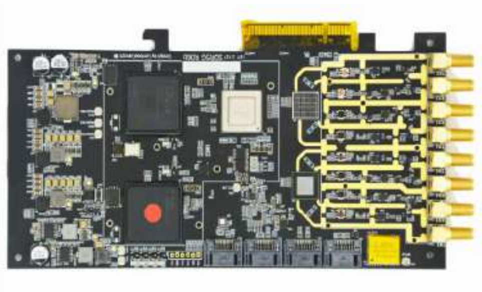
Layers	8L
Thickness	2.0mm
Material	S1000-2M+ SF202
Min. via	0.2mm
Min.line width/space:	4mil/5mil
Surface treatment	ENIG:2u"
Special process	Blind holes:L7-L8



PCBA







High-tech PCB&PCBA Manufacturer

05 PRODUCTION LINE »

PCB Production Equipment

Text printer
(HanYin, China)

Automatic Silkscreen Machine
(Dongyuan - Taiwan)

IR Tunnel Oven
(Xinjinhui, China)

Text Screen Printer
(Hengda, China)

Pre-treatment Machine
(Yuzhou, China)

Chemical Gold Line
(Yamei, China)

Post-treatment
(Yuzhou, China)

CNC V-cutting
(Yingtuo, Taiwan)

CNC gong machine
(Dazu, China)

Finished Product Cleaner
(Yuzhou, China)

AutomaticTesting Machine
(Kaima/Mingxin, China)

Flying Probe Tester
(Maichuangli, China)

PCBA Production Equipment

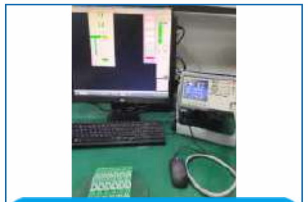
Zhengshi Printing Machine

Zhenhuaxing Spi

Yamaha Ysm20r High-speed
Smt Machine

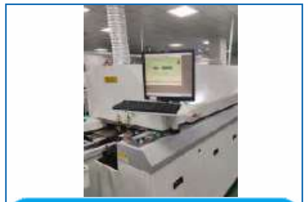
Yamaha Ysm10 High-speed
Smt Machine

shansiX-ray Machine



Intelligent First Article Detector

Zhenhuaxing Aoi



Jintuo Ten Temperature
Zone Reflow Welding

Intelligent Oven

BGA Rework station

Dual In-line Package Line

Nitto Lead-free Wave Soldering

Finished Product Assembly Line

Burn-In Room

Ten temperature zone reflow
soldering (ZTE-1000)

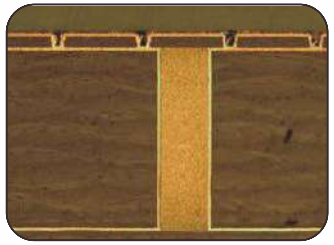
06 PROCESS » CAPABILITY

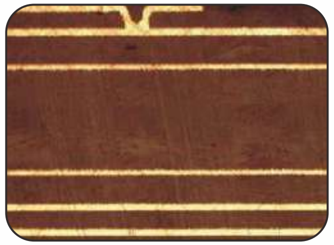
PCB Process Capability

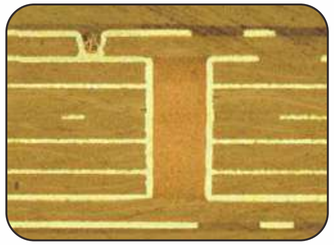
Series	Item		Specifications
1	Number of layer	Standard FR4 High TG	1–80 L (>=10 L must use High TG)
2	Product Type		mechanical blind buried hole, thick copper, semiconductor test board
		Multi–laminated blind buried hole	laminate for same side≤4 time
		HDI	1+N+1, 2+N+2,3+N+3
		High Frequency	Rogers series, Taconic series, Arlon series, Nelco series, F4BK, TP series
		Mixed lamination	Rogers+FR4
		Rigid–flex	≤20L
		FPC	≤10L
		metal material	copper material, AL material
3	Surface Treatment	Surface Treatment	HAL, HAL/LF, Enig, Immersion Silver, Immersion Tin, OSP, ENIPIG, Plating hard gold,Gold finger (contain segmented golden finger), Enig+OSP, Enig+gold finger, Immersion Tin+gold finger, Immersion Silver+gold finger
4	Board thickness	Board thickness	0.2–12.0mm
5	Finished Copper Thickness	Outer Layers (max)	20OZ
		Inner Layers (max)	10OZ
6	Line width /space	Min line width /space	3/3mil

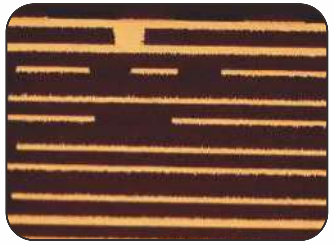
Microsection picture

One step HDI typical microsection picture

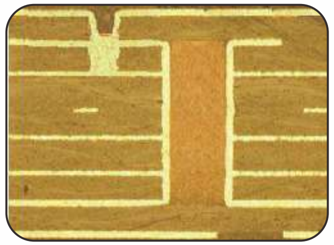

1+2+1

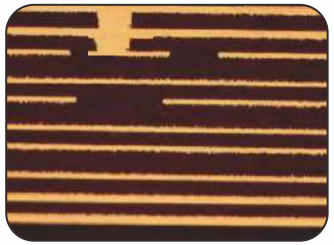

1+4+1

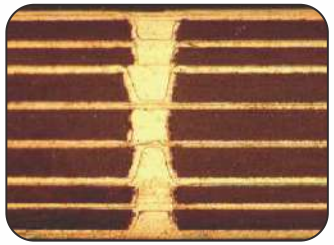

1+6+1

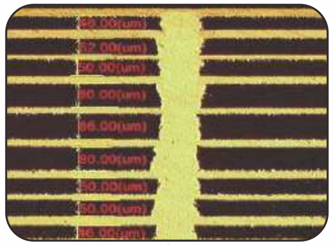

1+8+1

High step HDI typical microsection picture


2+4+2


2+6+2


3+2+3



4+2+4

07 PROCESS » CAPABILITY

Flex PCB / Rigid-flex PCB Technical Capability

No.	Item	Technical Capability	
		General	Special
1	Layer	1-20	HDI2 order
2	Material Types	General Flex、LCP、Panasonic、Dupont、SY、Taiflex	
3	Board thickness	0.04-2.0mm	
4	Board thickness Tolerance	±50um	
5	Board Size	480mm-1200mm	
6	Outline Tolerance	±0.05mm	
7	Dielectric layer thickness	0.013-0.150mm	
8	Out-layer copper thickness	18-280um	
9	Inner-layer copper thickness	18-105um	
10	Min line width	0.05mm	
11	Min line space	0.05mm	
12	Final hole size	0.1-6.35mm	0.05-6.35mm
13	Hole size Tolerance	±0.05mm	
14	Hole position tolerances	±0.05mm	
15	Plugged hole size	0.25-0.60mm	
16	Thickness aperture ratio	8:1	
17	Soldermask type	LPI	
18	Minimum Soldermask bridge width	0.075mm	
19	Minimum Soldermask isolation ring	0.05mm	
20	Cover	Yellow/ black/ white/ red	Other colors need to be
21	PI thickness	12.5-25um	
22	AD thickness	15-50um	
23	Stiffener	PI:0.05-0.25/ FR4 / Al / Copper	
24	Surface Finishes	ENIG/ mmAg / OSP / GoldFinger/ HAL / HAL-LF	
25	Impedance Tolerance	±10%	

SMT Project	Process Capability
PCB size	L810mm*W490mm~L50mm*W50mm
PCB Thickness	0.75mm~4.0mm
Substrate Material	Rigid Board,Flex Board,Flex–Rigid Board
Minimum Component size	01005(Imperial)
Minimum spacing Between Components	0.25mm(QFP/QFN/BGA)
Component Height	Up To 15mm
Printing Alignment Accuracy	±0.015mm
Installation Accuracy	±0.035mm
Actual Capacity	6 Million To 7 Million Points Per Day

08 OUR » SUPPLIERS

PCB Material Suppliers

DUPONT	ventec INTERNATIONAL GROUP 騰輝電子	ROGERS CORPORATION
廣信材料 KUANGSHUN	TAIYO INK	tuc 台燿科技 Taiwan Union Technology Corporation (TUC)
BERGQUIST	生益科技 SYTECH	南亞塑膠 NAN YA PLASTICS
isola	Panasonic	ITEQ INNOVATION · TEAMWORK · EXCELLENCE · QUALITY

PCBA Component Suppliers

NXP	intel	Micron	qorvo
安森美半导体 ON Semiconductor ON	ANALOG DEVICES	infineon	VISHAY
SAMSUNG	BROADCOM	RENESAS	LATTICE SEMICONDUCTOR
SEMTECH	AMD	TEXAS INSTRUMEN	ST